



## Automotive power Schottky rectifier







#### **Features**

- AEC-Q101 qualified
- Negligible switching losses
- · Low forward voltage drop for higher efficiency and extended battery life
- Low thermal resistance
- Surface mount miniature package
- · Avalanche capability specified
- ECOPACK®2 compliant component
- PPAP capable

### **Description**

This 150 V power Schottky rectifier is ideal for switch mode power supplies on up to 24 V rails and high frequency converters.

Packaged in SMA, the STPS1150-Y is intended for use in ECU (Engine Control Unit) and fly-back converters in automotive applications where low drop forward voltage is required to reduce power dissipation.

Product status					
STPS	STPS1150-Y				
Product summary					
Symbol Values					
I <sub>F(AV)</sub>	1 A				
V <sub>RRM</sub>	150 V				
<b>T</b> <sub>j (max)</sub> 175 °C					
V <sub>F(max)</sub>	0.67 V				



## 1 Characteristics

Table 1. Absolute ratings (limiting values, at 25 °C unless otherwise specified)

Symbol	Parameter			Unit
$V_{RRM}$	Repetitive peak reverse voltage, T <sub>j</sub> = -40 °C to	Repetitive peak reverse voltage, $T_j$ = -40 °C to +175 °C		
I <sub>F(RMS)</sub>	Forward rms current		15	Α
I <sub>F(AV)</sub>	Average forward current $T_L$ = 150 °C, $\delta$ = 0.5 square wave		1	Α
I <sub>FSM</sub>	Surge non repetitive forward current	t <sub>p</sub> = 10 ms sinusoidal	50	Α
P <sub>ARM</sub>	Repetitive peak avalanche power $t_p$ = 10 $\mu$ s, $T_j$ = 125 $^{\circ}$ C		108	W
T <sub>stg</sub>	Storage temperature range			°C
Tj	Operating junction temperature range <sup>(1)</sup>			°C

<sup>1.</sup>  $(dP_{tot}/dT_j) < (1/R_{th(j-a)})$  condition to avoid thermal runaway for a diode on its own heatsink.

Table 2. Thermal resistance parameters

Symbol	Parameter	Max. value	Unit	
R <sub>th(j-l)</sub>	Junction to lead	30	°C/W	

Table 3. Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
ı (1)	I <sub>R</sub> <sup>(1)</sup> Reverse leakage current	T <sub>j</sub> = 25 °C	V <sub>R</sub> = V <sub>RRM</sub>	-	0.2	1.0	μΑ
'R`		T <sub>j</sub> = 125 °C	VR - VRRM	-	0.2	1.0	mA
		T <sub>j</sub> = 25 °C	I <sub>F</sub> = 1 A	-	0.78	0.82	V
V <sub>F</sub> <sup>(2)</sup>	Forward voltage drep	T <sub>j</sub> = 125 °C		-	0.62	0.67	
VF <sup>(-)</sup>	Forward voltage drop	T <sub>j</sub> = 25 °C	I - 2 A	-	0.85	0.89	
		T <sub>j</sub> = 125 °C	I <sub>F</sub> = 2 A	-	0.69	0.75	

<sup>1.</sup>  $t_p = 5 \text{ ms}, \ \delta < 2\%$ 

To evaluate the conduction losses, use the following equation:

$$P = 0.59 \times I_{F(AV)} + 0.08 \times I_{F^{2}(RMS)}$$

DS7258 - Rev 3 page 2/9

<sup>2.</sup>  $t_p = 380 \ \mu s, \ \delta < 2\%$ 



### 1.1 Characteristics (curves)

Figure 1. Average forward power dissipation versus average forward current

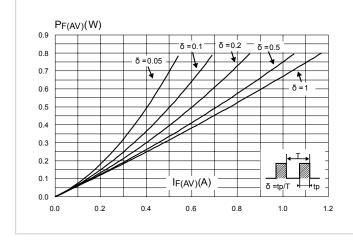


Figure 2. Average forward current versus ambient temperature ( $\delta$  = 0.5)

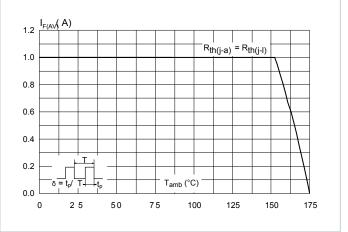


Figure 3. Normalized avalanche power derating versus pulse duration ( $T_i = 125$  °C)

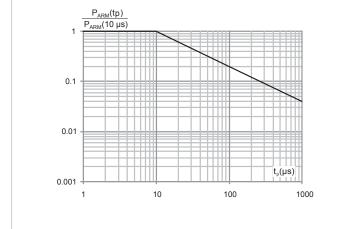


Figure 4. Relative variation of thermal impedance junction to ambient versus pulse duration

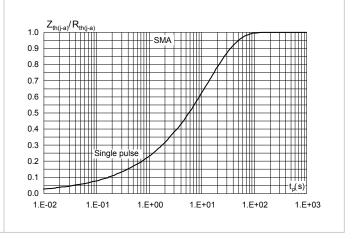


Figure 5. Reverse leakage current versus reverse voltage applied (typical values)

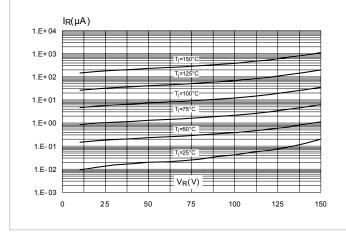
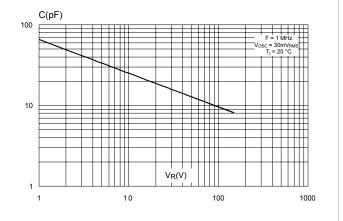


Figure 6. Junction capacitance versus reverse voltage applied (typical values)



DS7258 - Rev 3 page 3/9



Figure 7. Forward voltage drop versus forward current

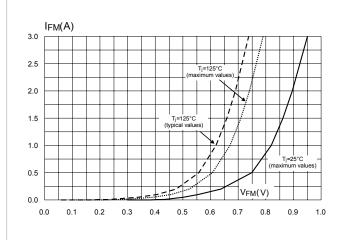
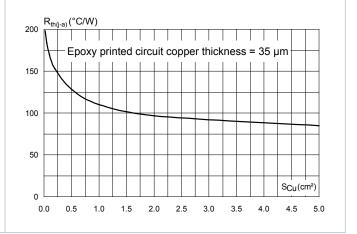


Figure 8. Thermal resistance junction to ambient versus copper surface under each lead (SMA)





## Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: www.st.com. ECOPACK<sup>®</sup> is an ST trademark.

## 2.1 SMA package information

- · Band shows cathode
- Epoxy meets UL94, V0

Figure 9. SMA package outline

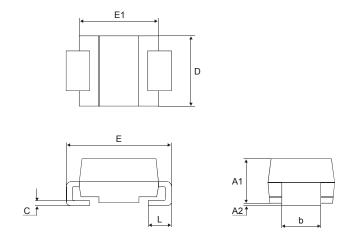


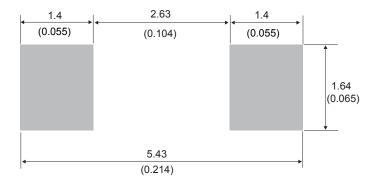
Table 4. SMA package mechanical data

	Dimensions				
Ref.	Millimeters		Inches		
	Min.	Max.	Min.	Max.	
A1	1.90	2.45	0.075	0.097	
A2	0.05	0.20	0.002	0.008	
b	1.25	1.65	0.049	0.065	
С	0.15	0.40	0.006	0.016	
D	2.25	2.90	0.089	0.114	
E	4.80	5.35	0.189	0.211	
E1	3.95	4.60	0.156	0.181	
L	0.75	1.50	0.030	0.059	

DS7258 - Rev 3 page 5/9



Figure 10. SMA recommended footprint in mm (inches)



DS7258 - Rev 3 page 6/9



# 3 Ordering Information

**Table 5. Ordering information** 

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPS1150AY	1150Y	SMA	0.068 g	5000	Tape and reel



## **Revision history**

Table 6. Document revision history

Date	Version	Changes
02-Nov-2011	1	Initial release.
02-May-2012	2	Updated Table 3.
16-Apr-2018	3	Updated Figure 3. Normalized avalanche power derating versus pulse duration ( $T_j$ = 125 °C), Table 2. Thermal resistance parameters and Table 1. Absolute ratings (limiting values, at 25 °C unless otherwise specified). Removed figure 4 and figure 5.



#### **IMPORTANT NOTICE - PLEASE READ CAREFULLY**

STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2018 STMicroelectronics – All rights reserved

DS7258 - Rev 3 page 9/9